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BY -

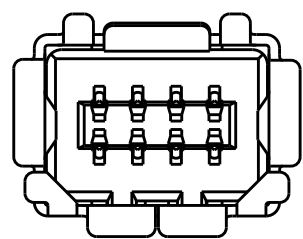
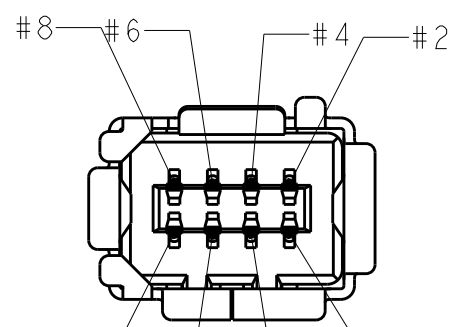
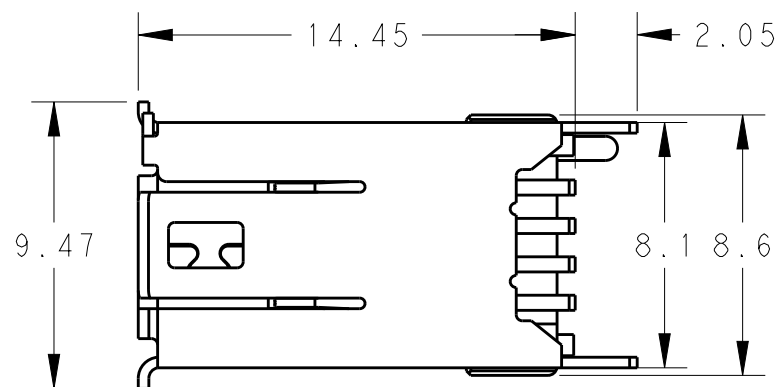
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LOC

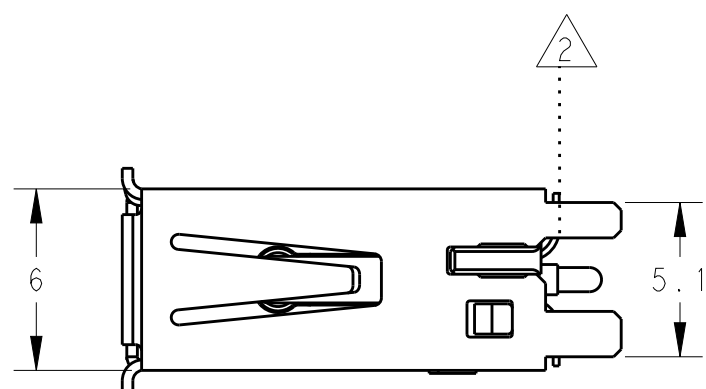
DIST

REVISIONS

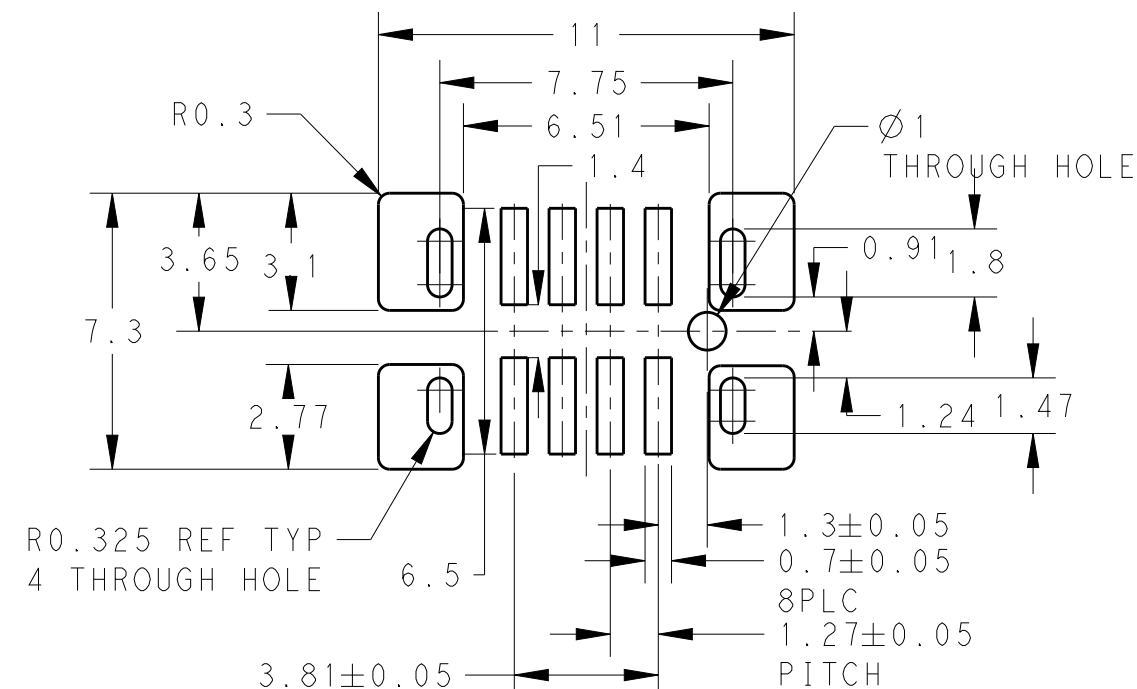
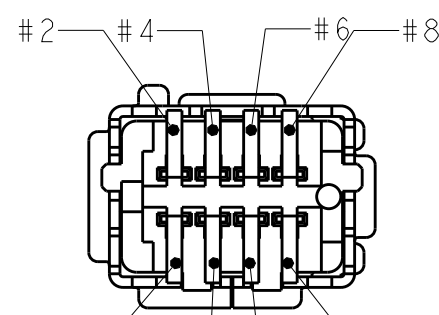
P	LTR	DESCRIPTION	DATE	DWN	APVD
	A	NEW RELEASE	14DEC2015	L.Z.	X.X.
	B	ECR-16-006831 PACKAGE TRAY CHANGE	04MAY2016	L.Z.	X.X.

2271656-2
TYPE II2271656-1
TYPE I

CIRCUIT NO



CIRCUIT NO

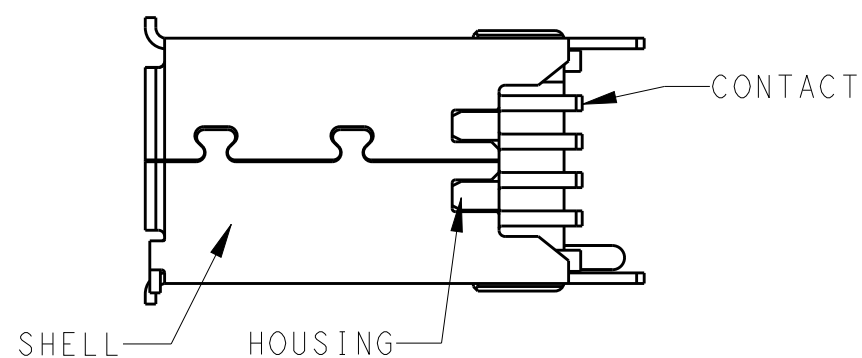


RECOMMENDED BOARD DIMENSION

t=1.6

SCALE 5:1

GENERAL TOL.: ±0.1



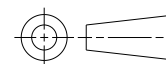
NOTES:

- 1 MATERIAL AND FINISH
CONTACT: COPPER ALLOY
UNDER ALL SURFACE NICKEL 1.27µm MIN.
TOP CONTACT AREA: GOLD 0.5µm MIN
SOLDERING AREA: TIN PLATE
HOUSING: THERMO PLASTIC(UL94V-0)
SHELL: COPPER ALLOY
UNDER ALL SURFACE NICKEL
TOP ALL SURFACE TIN
- 2 COPLANARITY 0.1 MAX
(IN 8 TIPS OF CONTACTS)
- 3 GENERAL TOL.: ±0.3; ±5°

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:

mm

TOLERANCES UNLESS
OTHERWISE SPECIFIED:

0 PLC ±
1 PLC ±
2 PLC ±
3 PLC ±
4 PLC ±
ANGLES ±

MATERIAL

FINISH

DWN 01DEC2015

LEAR ZHANG

CHK 01DEC2015

KOBBOY ZHAO

APVD 01DEC2015

XU XIANG

PRODUCT SPEC

108-106087

APPLICATION SPEC

-

WEIGHT

-

Customer Drawing

TE

TE Connectivity

NAME
SMT VERTICAL MINI I/O RECEPTACLE
1.27mm PITCH

SIZE CAGE CODE DRAWING NO RESTRICTED TO

A3 - C-2271656

SCALE 4:1 SHEET 1 OF 3 REV B

